

Title (en)

METHOD OF MANUFACTURING AN ELECTRICAL DEVICE

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER ELEKTRISCHEN VORRICHTUNG

Title (fr)

PROCEDE DE FABRICATION D'UN DISPOSITIF ELECTRIQUE

Publication

EP 0533760 B1 19991117 (EN)

Application

EP 91910990 A 19910528

Priority

- SE 9001990 A 19900605
- SE 9100375 W 19910528

Abstract (en)

[origin: WO9119297A1] An electrical device, especially an overcurrent protective device, with a polymer composition arranged between two electrodes comprising a polymer material and an electrically conductive powdered material, distributed in the polymer material, is manufactured by mixing the polymer material in thermoplastic state and in powdered state with a grain size of less than 100 μm, and of less than 40 μm in at least 50 % of the material, in solid, dry state with the electrically conductive powdered material in a grain size of less than 100 μm into a mixture in which the polymer material constitutes at least 30 per cent and the electrically conductive powdered material at least 20 per cent of the total volume of these materials, and by subjecting the mixture together with the electrodes to a pressing and a heating to a temperature at which the polymer material melts at least on the surface of the grains while forming a permanently coherent body of the mixture and while fixing the electrodes to the coherent body.

IPC 1-7

H01B 1/20; H01B 1/22; H01B 1/24; H01B 5/16

IPC 8 full level

H01B 1/20 (2006.01); **H01B 1/22** (2006.01); **H01B 1/24** (2006.01); **H01C 7/02** (2006.01)

CPC (source: EP)

H01B 1/20 (2013.01); **H01B 1/22** (2013.01); **H01B 1/24** (2013.01); **H01C 7/027** (2013.01)

Designated contracting state (EPC)

AT BE CH DE DK ES FR GB GR IT LI LU NL SE

DOCDB simple family (publication)

WO 9119297 A1 19911212; AT E186793 T1 19991215; DE 69131787 D1 19991223; DE 69131787 T2 20000621; EP 0533760 A1 19930331; EP 0533760 B1 19991117; JP 2836959 B2 19981214; JP H05508055 A 19931111; SE 468026 B 19921019; SE 9001990 D0 19900605; SE 9001990 L 19911206

DOCDB simple family (application)

SE 9100375 W 19910528; AT 91910990 T 19910528; DE 69131787 T 19910528; EP 91910990 A 19910528; JP 51058391 A 19910528; SE 9001990 A 19900605